

Name:

Date:

Class:

Photolithography Lab Worksheet

Problem Statement:

How can we create the sharpest, most accurate pattern on a glass disc using photolithography techniques adapted for a classroom?

Objective: Simulate the photolithography process used in semiconductor manufacturing by using gel nail polish as a photoresist and a UV lamp to develop a masked pattern on a glass disc. For each iteration of your work, you will follow the same basic procedures, outlined below.

Success Criteria:

- Pattern edges are sharp.
- Mask image matches final result.
- Unintended exposure is minimal.

Materials Needed

- 1 borosilicate glass disc
- acetone
- isopropyl alcohol (IPA)
- cotton swabs or lens wipes
- gel nail polish (clear, UV-curable)
- mask material (construction paper, foil, or printed transparency)

- UV light source (shared)
- water (for final rinse)
- tweezers or gloves
- timer or stopwatch
- small tray or petri dish for developing
- (optional) turntable
- (optional) microscope or magnifying lens

Step 1: Brainstorm, Plan, and Design

1. Sketch 2-3 possible mask designs.
2. Choose one based on:
 - a. Level of detail (too fine may blur).
 - b. Contrast between exposed/unexposed regions.
 - c. Ease of cutting.
3. Predict how UV light might interact with the design.
4. Using construction paper or foil, cut a piece that is larger than the glass disc.
5. Create a pattern and cut it into the material. The pattern can be anything you like, and should fully encompass the area in which the nail polish was applied.

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Possible mask designs

Sketch #1

Sketch #2

Sketch #3

Chosen Design

How do you think UV light might interact with your chosen design?

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Step 2: Apply “Photoresist”

1. Put on gloves.
2. Clean the glass disc in the following order:
 - a. Wipe with acetone.
 - b. Wipe with IPA.
3. Dry with a lint-free cloth or allow disc to air dry.
4. Using a sponge, foam brush, or soft applicator, apply a thin, even layer of clear gel nail polish (photoresist) across the glass disc.
5. Optional: After applying the clear gel nail polish to the glass disc, place the glass disc onto a turntable and lightly spin it to evenly spread the nail polish.
6. Let painted glass disc sit for 1–2 minutes to allow the nail polish to self-level.

Step 3: Mask and UV Exposure

1. Place your opaque mask over the coated glass disc.
2. Ensure your mask lies flat and as close to the glass disc as possible. Note: You may need to be creative with spacers. The closer the mask is to the glass, the sharper your results will be.
3. **Engineering sub-problem:** How can you create a small, even gap between the mask and the glass disc to prevent smearing while keeping the mask close enough for a clear UV image?

4. Place under the UV light source (perpendicular, fixed height) and expose the sample for the time specified by your teacher.
5. **Predict:** How does distance affect the sharpness of the image?

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Step 4: Develop the Pattern

1. Carefully remove the mask.
2. Gently swirl disc or dab the disc in a tray of acetone; avoid scrubbing to prevent damaging the cured pattern.
3. Rinse the disc with water to remove residue and dry gently.
4. Optional: Rest the glass disc on a hot plate heated to 50° C for 90 seconds.

Step 5: Analyze

1. Observe the pattern that remains on the glass.
2. Compare this pattern with your original mask design and the success criteria. Record your answers below, addressing the following:
 - How well did the image transfer?
 - Are edges sharp or blurry?
 - Are there overexposed or underexposed regions?
 - Did mask alignment work as intended?
 - What might have caused any flaws (e.g., thickness, mask gap, light angle, exposure time)?
3. List what you would do differently to improve your mask design. Hint: Think about what you can change (e.g., thickness of gel nail polish, mask gap, light angle, exposure time).

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Step 6: Iterate and Improve the Design

1. Revise your mask (e.g., simplify shapes, improve opacity, reinforce edges).
2. Adjust photoresist application (e.g., thinner, smoother, more level).
3. Change exposure strategy (e.g., distance, time, alignment).
4. Perform Steps 2-5 in this worksheet.
5. Document what you changed and why. Note: This mirrors actual semiconductor process optimization. Also, note how your changes improved or didn't improve your design.